

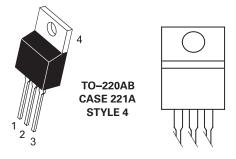
Surface Mount - 250V > MAC3030-8

# MAC3030-8





#### **Pin Out**



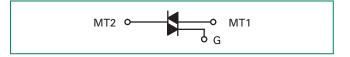
## **Description**

Designed primarily for full-wave AC control applications, such as light dimmers, motor controls, heating controls and power supplies; or wherever full-wave silicon gate controlled solid-state devices are needed. Triac type thyristors switch from a blocking to a conducting state for either polarity of applied main terminal voltage with positive or negative gate triggering.

#### **Features**

- Blocking Voltage to 250 Volts
- All Diffused and Glass Passivated Junctions for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Gate Triggering Guaranteed in Four Modes (Quadrants)
- Pb-Free Packages are Available

#### **Functional Diagram**



## Additional Information







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Specifications are subject to change without notice.
Revised: 08/30/17

## **Maximum Ratings** $(T_J = 25^{\circ}C \text{ unless otherwise noted})$

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage (Note 1) (– 40 to 1125°C, Sine Wave, 50 to 60 Hz, Gate Open)	V <sub>DRM</sub> , V <sub>RRM</sub>	250	V
On-State RMS Current ( $T_c = +70$ °C) Full Cycle Sine Wave, 50 to 60 Hz	I <sub>T (RMS)</sub>	8.0	А
Peak Non-Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz, $T_{\rm C}$ = +25°C) Preceded and followed by rated current	I <sub>TSM</sub>	80	А
Circuit Fusing Consideration (t = 8.3 ms)	l²t	26	A <sup>2</sup> sec
Peak Gate Current, (TC = $+70$ °C, Pulse Width = $10 \mu s$ )	I <sub>GM</sub>	2.0	А
Peak Gate Power ( $T_c = +70^{\circ}$ C, Pulse Width = 10 µs)	P <sub>GM</sub>	20	W
Average Gate Power ( $T_c = +70^{\circ}$ C, t = 8.3 ms)	P <sub>G (AV)</sub>	0.35	W
Operating Junction Temperature Range	T <sub>J</sub>	-40 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

## **Thermal Characteristics**

Rating		Symbol	Value	Unit
Thermal Resistance,	Junction-to-Case (AC) Junction-to-Ambient	R <sub>8JC</sub> R <sub>8JA</sub>	2.0 62.5	°C/W
Maximum Lead Temperature for Solderin 10 seconds	ng Purposes, 1/8" from case for	T <sub>L</sub>	260	°C

<sup>1.</sup> V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

## **Electrical Characteristics - OFF** $(T_j = 25^{\circ}\text{C unless otherwise noted})$ ; Electricals apply in both directions

Characteristic		Symbol	Min	Тур	Max	Unit
Peak Repetitive Blocking Current	T <sub>J</sub> = 25°C	l <sub>DRM</sub> ,	-	-	10	μА
$(V_D = V_{DRM} = V_{RRM}; Gate Open)$	T <sub>J</sub> = 125°C	I <sub>RRM</sub>	-	-	2.0	mA

## **Electrical Characteristics** · **ON** $(T_J = 25^{\circ}\text{C unless otherwise noted; Electricals apply in both directions)$

Characteristic			Min	Тур	Max	Unit
Peak On–State Voltage ( $I_{TM} = \pm 11$ A Peak, Pulse Width $\leq 2$ ms, Duty Cycle $\leq 2\%$ )		V <sub>TM</sub>	-	1.2	1.65	V
	MT2(+), G(+)		-	12	50	
Gate Trigger Current	MT2(+), G(-)		-	12	50	A
(Continuous dc) $(V_D = 12 \text{ V}, R_L = 100 \text{ Ohms})$	MT2(-), G(-)		50	mA		
	MT2(-), G(+)		-	35	75	
	MT2(+), G(+)		-	0.9	2.0	
Gate Trigger Voltage	MT2(+), G(-)	V <sub>GT</sub>	-	0.9	2.0	\ <u>\</u>
(Continuous dc) $(V_D = 12 \text{ V}, R_L = 100 \Omega)$	MT2(-), G(-)		_	1.1	2.0	V
	MT2(-), G(+)		_	1.4	2.5	
Gate Non-Trigger Voltage (Continuous DC), ( $V_D = 12 \text{ V}, T_C = 110^{\circ}\text{C}, R_L = 100 \Omega$ ) All Four Quadrants		V <sub>GD</sub>	0.2	-	-	V
Holding Current ( $V_D = 12 V_{dc}$ , Gate Open, Initiating Current = $\pm 200 \text{ mA}$ ))		I <sub>H</sub>	-	6.0	50	mA
Turn-On Time (Rated $V_{DRM'}$ , $I_{TM} = 11 \text{ A}$ ) ( $I_{GT} = 120 \text{ mA}$ , Rise Time = 0.1 s, Pulse Width = 2 s)		t <sub>gt</sub>	-	1.5	_	μs

## **Dynamic Characteristics**

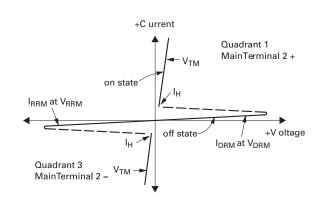
Characteristic	Symbol	Min	Тур	Max	Unit
Critical Rate of Rise of Commutation Voltage ( $V_D$ = Rated $V_{DRM'}$ $I_{TM}$ = 14 A, Commutating di/dt = 5.0 A/ms, Gate Unenergized, $T_C$ = 70°C)	(di/dt)c	-	5.0	-	A/ms
Critical Rate of Rise of Off-State Voltage $(V_D = Rated V_{DRM'} Exponential Waveform, Gate Open, T_C = \pm 70^{\circ}C)$	dv/dt	-	100	-	V/µs



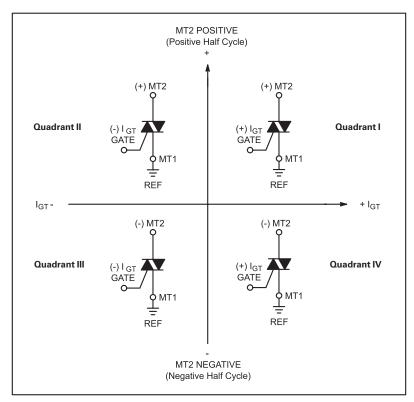
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## **Voltage Current Characteristic of SCR**

Symbol	Parameter
$V_{DRM}$	Peak Repetitive Forward Off State Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
$V_{_{\mathrm{RRM}}}$	Peak Repetitive Reverse Off State Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
V <sub>TM</sub>	Maximum On State Voltage
I <sub>H</sub>	Holding Current



## **Quadrant Definitions for a Triac**



All polarities are referenced to MT1.

With in-phase signals (using standard AC lines) quadrants I and III are used.



Figure 1. Current Derating

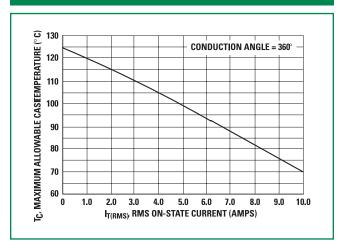


Figure 3. Maximum On-State Characteristics

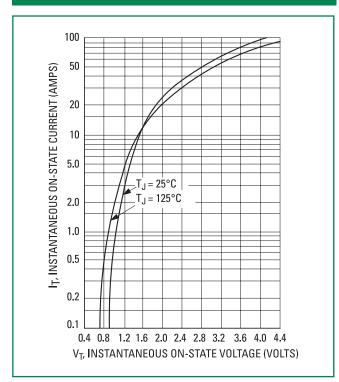


Figure 2. Power Dissipation

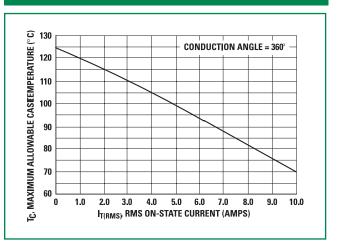


Figure 4. Maximum Non-Repetitive Surge Current

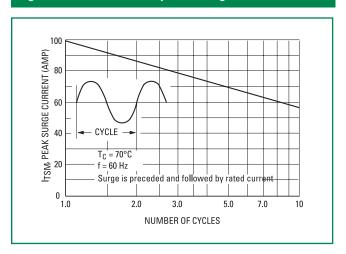
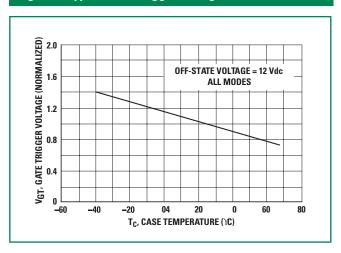
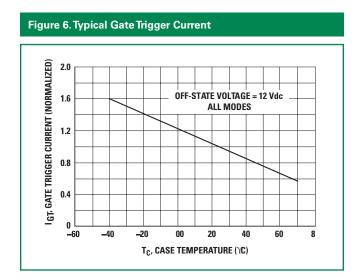


Figure 5. Typical Gate Trigger Voltage





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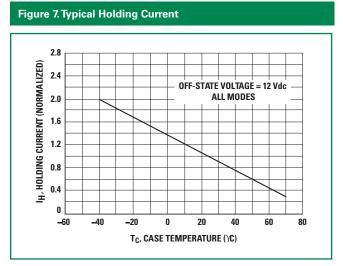
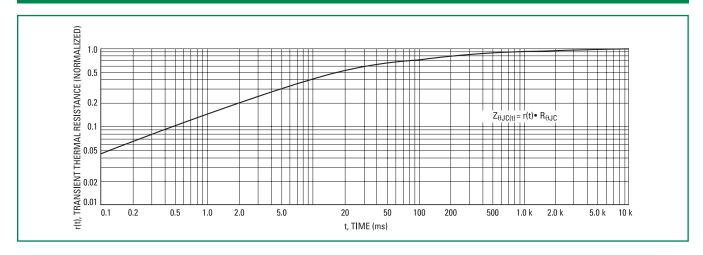


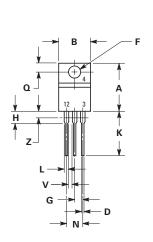
Figure 8. Thermal Response

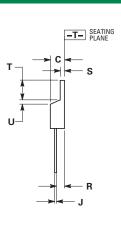




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#### **Dimensions**

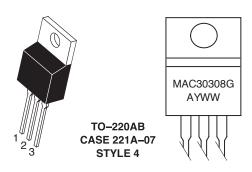




	Incl	nes	Millim	neters	
Dim	Min	Max	Min	Max	
А	0.570	0.620	14.48	15.75	
В	0.380	0.405	9.66	10.28	
С	0.160	0.190	4.07	4.82	
D	0.025	0.035	0.64	0.88	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.155	2.80	3.93	
J	0.014	0.022	0.36	0.55	
K	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
N	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
V	0.045		1.15		
Z		0.080		2.04	

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

## **Part Marking System**



MAC3030-8 = Standard Device Code MAC30308G = Pb-Free Device Code

A= Assembly Location Y= Year

Y= Year WW = Work Week

Pin Assignment	
1	Main Terminal 1
2	Main Terminal 2
3	Gate
4	Main Terminal 2

#### **Ordering Information**

Device	Package	Shipping
MAC3030-8	TO-220AB	500 Units/ Bulk
MAC3030-8G	TO-220AB (Pb-Free)	500 Units/ Bulk

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